

Abstract Of The Disclosure

A method for producing a component is provided, in particular a deformation sensor, having a sensor element which includes at least one region that is sensitive with respect to expansion or compression, as well as electrical structures which are in connection therewith. To this
5 end, a sacrificial layer is produced on or within a substrate and an activatable layer on top of the sacrificial layer, the sensitive region and at least a portion of the electrical structures being positioned on top or within an activatable layer, and a circumferential trench is produced around the region of the sensor element to be produced and having the sensitive region and the portion of the electrical structures, the trench being interrupted by at least one connecting
10 point, which connects the region of the sensor element to the portion of the activatable layer lying outside the circumferential trench. This is followed by a removal of the sacrificial layer underneath the region of the sensor element, a fixation of the region of the sensor element with the aid of a holding device, rupturing of the connecting points and a transfer of the sensor element, fixated by the holding device, and connecting a carrier to the component as
15 well as joining with a carrier to the component.